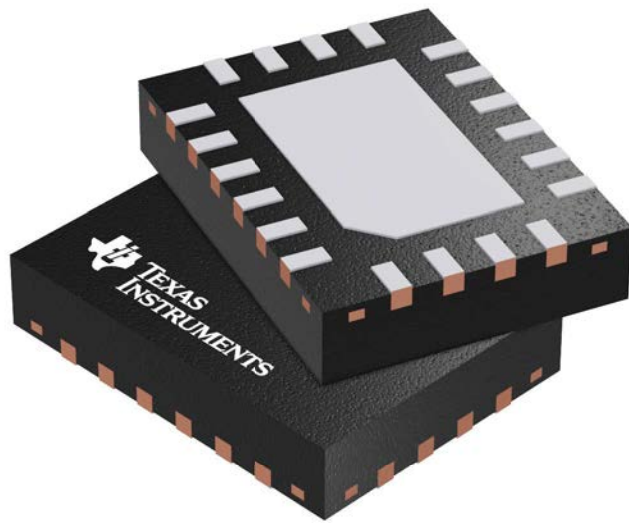


GENERIC PACKAGE VIEW

RVC 20

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4209819/B

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